## Sen Mei

## List of Publications by Year in descending order

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1937685 2272923 9 100 4 4 citations h-index g-index papers 9 9 9 174 docs citations citing authors all docs times ranked

#	Article	IF	CITATIONS
1	Reliability and Breakdown Study of Erase Gate Oxide in Split-Gate Non-Volatile Memory Device., 2020,,.		O
2	Boron Vacancies Causing Breakdown in 2D Layered Hexagonal Boron Nitride Dielectrics. IEEE Electron Device Letters, 2019, 40, 1321-1324.	3.9	16
3	Conductive Atomic Force Microscope Study of Bipolar and Threshold Resistive Switching in 2D Hexagonal Boron Nitride Films. Scientific Reports, 2018, 8, 2854.	3.3	55
4	Impact of Carbon Doping on Polysilicon Grain Size Distribution and Yield Enhancement for 40-nm Embedded Nonvolatile Memory Technology. IEEE Transactions on Device and Materials Reliability, 2018, 18, 64-69.	2.0	4
5	Stochastic Modeling of FinFET Degradation Based on a Resistor Network Embedded Metropolis Monte Carlo Method. IEEE Transactions on Electron Devices, 2018, 65, 440-447.	3.0	6
6	Area and pulsewidth dependence of bipolar TDDB in MgO magnetic tunnel junction. , $2018,$ , .		7
7	Statistical basis and physical evidence for clustering model in FinFET degradation. , 2017, , .		2
8	Multiphysics based 3D percolation framework model for multi-stage degradation and breakdown in high- $\hat{\mathbb{I}}^{\circ}$ $\hat{\mathbb{I}}$ and $\hat{\mathbb{I}}$ interfacial layer stacks. , 2016, , .		2
9	New understanding of dielectric breakdown in advanced FinFET devices — physical, electrical, statistical and multiphysics study. , 2016, , .		8